



# 48 Activated Rosin Cored Wire For Lead-bearing and Lead-free alloys

## **Product Description**

Kester 48 Activated Rosin Flux for cored solder wire was developed for lead-free applications to enable soldering of most common metals. Kester 48 has performance characteristics far exceeding standard RA fluxes. Kester 48 builds on the performance of its predecessor Kester 44 with "instant-action" wetting to provide fast and reliable solder joints.

#### **Performance Characteristics:**

- Unparalleled wetting performance
- Excellent solderability and fast wetting to a variety of surface finishes
- Eliminates the need and expense of cleaning
- · Low smoke and odor
- Low spattering
- Classified as ROL1 per J-STD-004

## Kester 48 vs. Kester 44

- Kester 48 provides a higher level of activity than Kester 44, see Spread Test opposite.
- Kester 48 dramatically reduces splattering by 50+% over Kester 44.
- Kester 48 residues are transparent and nearly colorless compared to the traditional amber appearance of Kester 44.
- Kester 48 was designed for lead-free alloys.

# **RoHS Compliance**

This product meets the requirements of the RoHS (Restriction of Hazardous Substances) Directive, 2002/95/EC Article 4 for the stated banned substances. (Applies only if this core flux is combined with a lead free alloy)

# **Reliability Properties**

Copper Mirror Corrosion: Low
Tested to J-STD-004 JPC-TM-650 Method 2 3 32

Corrosion Test: Low

Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Silver Chromate: Fail

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

**Chloride and Bromides:** 1.05% Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Fluorides by Spot Test: Pass
Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

SIR, IPC (typical): Pass

Tested to J-STD-004. IPC-TM-650. Method 2.6.3.3

	<u>Blank</u>	<u>48</u>
Day 1	1.6 ×10 <sup>10</sup> Ω	$1.1 \times 10^{10} \Omega$
Day 4	1.2×10 <sup>10</sup> Ω	$9.2 \times 10^9 \Omega$
Day 7	1.1 ×10 <sup>10</sup> Ω	$8.6  imes 10^9 \ \Omega$

## Spread Test (typical):

Tested to J-STD-004, IPC-TM-650, Method 2.4.46

	Area of Spread mm <sup>2</sup> (in <sup>2</sup> )	
Flux Core Solder	Sn96.5Ag3.0Cu0.5	Sn63Pb37
285 Mildly Activated Rosin	213 (0.33)	335 (0.52)
275 No-Clean	219 (0.34)	361 (0.56)
44 Activated Rosin	220 (0.34)	342 (0.53)
48 No-Clean	245 (0.38)	419 (0.65)

# **Application Notes**

## Availability:

Kester 48 is available in a wide variety of alloys, wire diameters and flux percentages. For most applications, Sn63Pb37or Sn96.5Ag3.0Cu0.5 is used. Consult the alloy temperature chart in Kester's product catalog for a comprehensive alloy list. The standard wire diameter for most applications is 1.00mm (0.031in). Wire diameters range from 0.25 - 6.00mm (0.010 to 0.250in). A "Standard Wire Diameters" chart also is also included in Kester's product catalog. The amount of flux in the wire dictates the ease of soldering for an application. For most applications, core 66 (3.3% flux by weight) is recommended. Other core sizes, 50 and 58, (1.1% and 2.2% respectively) are available. Kester 48 is packaged on spools of different sizes to accommodate a variety of applications.

#### **Process Considerations:**

Solder iron tip temperatures are most commonly between 315-371°C (600-700°F) for Sn63Pb37 and Sn62Pb36Ag02 alloys and 371-427°C (700-800°F) for lead-free alloys. Heat both the land area and component lead to be soldered with the iron prior to adding Kester 48 cored wire. Apply the solder wire to the land area or component lead. Do not apply the wire directly to the soldering iron tip. If needed, Kester 186, 186-18 or 1544 activated flux may be used as a compatible liquid flux to aid in reworking soldered joints.

## Cleaning:

The 48 residues are non-conductive, non-corrosive and do not require removal in most applications. The flux residues are comparable to a conventional RA. If residue removal is required, call Kester Technical Support.

## Storage, Handling, and Shelf Life:

Storage must be in a dry, non-corrosive environment. The surface may lose its shine and appear a dull shade of grey. This is a surface phenomena and is not detrimental to product functionality. Flux cored solder wire has a limited shelf life determined by the alloy used in the wire. For alloys containing > 70% lead, the shelf life is two years from date of manufacture. Other alloys have a shelf life of three years from date of manufacture.

#### **Health & Safety:**

This product, during handling or use, may be hazardous to health or the environment. Read the Material Safety Data Sheet and warning label before using this product.

World Headquarters: 515 E. Touhy Avenue, Des Plaines, Illinois, 60018 USA

Phone: (+1) 847-297-1600 • Email: customerservice@kester.com • Website: www.kester.com

Asia Pacific Headquarters
500 Chai Chee Lane
Singapore 469024
(+65) 6449-1133
customerservice@kester.com.sq

European Headquarters
Ganghoferstrasse 45
D-82216 Gernlinden
Germany
(+49) 8142-47850
customerservice@kester-eu.com

Japanese Headquarters 20-11 Yokokawa 2-Chome Sumida-Ku Tokyo 130-0003 Japan (+81) 3-3624-5351 ipsales@kester.com.sq

The data recommendations presented are based on tests, which we consider reliable. Because Kester has no control over the conditions of use, we disclaim any responsibility connected with the use of any of our products or the information presented. We advise that all chemical products be used only by or under the direction of technically qualified personnel who are aware of the potential hazards involved and the necessity for reasonable care in their handling. The technical information contained herein is consistent with the properties of this material but should not be used in the preparation of specifications as it is intended for reference only. For assistance in preparing specifications, please contact your local Kester office for details.